REMARKS

Claims 7-9, 21-23, 30-32 are pending in this application. Claims 1-6, 10-20, and 24-29 have been canceled without prejudice or disclaimer. Claims 7, 9, 21, 30 and 32 have been amended. No new matter has been added.

Amendments to Claims 7, 30 and 32:

Applicants filed a Preliminary Amendment to correspond with the amendments made to the claims under PCT Article 19 in the International application. In the Preliminary Amendment, Applicants added the phrase, "thick film electrode being formed by plating" in claim 7 and "said thick film electrode being formed by plating or printing" in claim 30. According to the present amendment, these phrases are deleted. Further, claim 32 had been amended in the Preliminary Amendment to delete the phrase " a metallic layer that is formed by any of plating, vacuum evaporation, chemical vapor deposition, and screen printing" and this phrase has been added back into the claim by the present amendment. Entry of the amendments to the claims is respectfully requested.

Rejections under 35 USC §102

Claims 7-9 stand rejected under 35 USC §102 as being anticipated by Kusunoki et al. (JP 11-120898).

The Office Action alleges that Kusunoki et al. disclose an electron source comprising of a plurality of electron source elements (Fig. 24 & Fig. 19), each of which has a structure in which a bottom electrode, an insulating layer, and a top electrode are laminated in this order, and a plurality of bus electrodes that are connected to apply a driving voltage to an electron source element, wherein the bus electrode comprises a thin film electrode connected to an electrode and a thick film electrode connected to the thin film electrode. Kusunoki et al. is relied upon for disclosing that the thick film electrode has a film thickness thicker than that of a thin film electrode and the thin film electrode comprises tungsten film. Also, with respect to claim 8, Kusunoki is relied upon for disclosing that the thin film electrode and thick film electrode have an open area where the insulating layer is formed and wherein the top electrode

covers the thin film electrode that is exposed in the open area provided in the thick film electrode (referring to Fig. 19 of the reference).

Claim 7 sets forth that the thin film electrode is integrated with the top electrode, which corresponds to the description of the Embodiments 2 and 3 of the present invention. Thus, "a thin film electrode that is integrated with the top electrode" is claimed, as shown in lines 14-15 of claim 7. In particular, the top electrode 13 of the invention is also used as a bus electrode lower layer, so it is possible to prevent the top electrode 13 from being broken by a difference in level in the electron-emitting portion. (see page 19, lines 8-11 of the specification). The cited reference does not disclose that the thin film electrode (15A) is integrated with the top electrode (13), and therefore this aspect of the claimed combination is not shown or suggested by the reference. Therefore, claims 7-9 are not anticipated by Kusunoki et al. (JP 11-120898).

Claim rejections under 35 USC §103

Claims 21-23 and 30-32 stand rejected under 35 USC §103(a) as being unpatentable over Kusunoki (JP11-120898). Claims 21 and 30, which are the independent claims, set forth the limitation that a thin film electrode is integrated with the top electrode, corresponding to the descriptions in Embodiments 2, 3 of the present specification, which is also found in claim 7. Therefore, claims 21-23 and 30-32 are patentable over Kusunoki et al. (JP 11-120898) for the same reasons mentioned with respect to the patentability of claims 7-9 over Kusunoki et al. Therefore, the rejection under 35 USC §103 should be withdrawn.

Conclusion

In view of the foregoing amendments and remarks, Applicants contend that the above-identified application is now in condition for allowance. Accordingly, reconsideration and reexamination are requested.

Respectfully submitted,

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